

Promex Quik-Pak Features Air Cavity Plastic and Overmolded QFNs at Electronic Packaging Symposium, September 18-19, Binghamton, New York

Santa Clara, CA – August 27, 2018 – The [Quik-Pak](#) Division of [Promex](#) will exhibit air cavity plastic QFNs and overmolded QFNs at the 30th Annual Electronics Packaging Symposium (EPS), September 18-19, 2018 in Binghamton, New York. Considered by many the premier electronics manufacturing conference in the Northeast, the event's format will give attendees ample time to confer with Promex Sales Engineer Colleen Ewanich and East Coast & Europe Technical Sales Manager Bill Lawrence about packaging requirements and challenges.

Quik-Pak's [air cavity plastic QFN packages](#), also known as Open-molded Plastic Packages or OmPPs, feature gold plating for wire bondability, RoHS/REACH-compliant green molding compound, highly conductive short interconnects and JEDEC outlines. Matching ceramic, plastic, quartz or glass lids with b-stage epoxy seals are available. More than 30 off-the-shelf sizes are in stock for prototype, mid-volume and production-volume requirements. Custom designs are also available.

Quik-Pak's [overmolded, open-tooled QFN packages](#) for quick-turn engineering builds, high mix/low volume assembly and onshore volume production are available for purchase off the shelf in over 35 designs, from 2x2 mm to 12x12 mm, with multiple thicknesses. Five-day delivery of assembled QFNs is standard. All QFNs are RoHS compliant and utilize NiPdAu-plated lead frames. Custom designs are also available with quick lead-times.

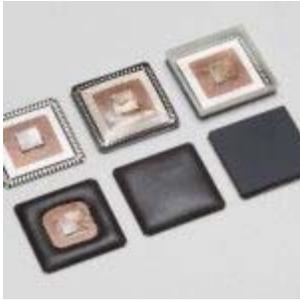
ABOUT EPS 2018

The 30th annual Binghamton University and GE Electronics Packaging Symposium brings together more than 250 attendees from academia, industry and government, including key decision makers and future leaders of the electronics packaging industry. This year's event features more than 50 technical sessions, including an IEEE Electronics Packaging Society-sponsored workshop on Heterogeneous Integration.

ABOUT PROMEX QUIK-PAK

The Quik-Pak Division of Promex provides IC packaging, assembly and wafer preparation services for prototype to full-production needs from its ISO 9001:2008 certified, ITAR registered facility in San Diego, California. More information is available by contacting East Coast & Europe Technical Sales Manager Bill Lawrence at 802-309-0327 or Quik-Pak at 858-674-4676, <http://www.icproto.com>.

Promex provides design for manufacturing services coupled with materials science expertise and broad assembly capabilities for small- to mid-volume onshore production. Services include RoHS-optimized SMT, wafer thinning, dicing, wirebond, flip chip, overmolding and Class 100/Class 1000 cleanrooms. IC packaging, Located in Silicon Valley since 1975, Promex is ISO 13485:2016 and ISO 9001:2015 certified, IPC certified and ITAR registered. More information is available by contacting Sales Engineer Colleen Ewanich or Promex at 408-496-0222, <http://www.promex-ind.com>.



[Air cavity plastic QFN packages](#) for RF/microwave, MEMS and sensor applications and [overmolded QFN packages](#) for quick-turn engineering builds, high mix/low-volume assembly and onshore volume production are available from Promex Quik-Pak in over 35 off-the-shelf designs.